

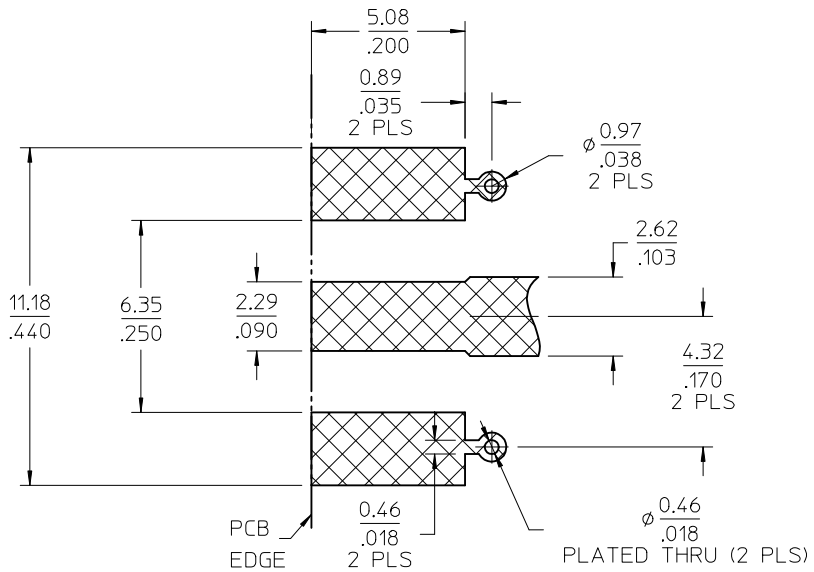
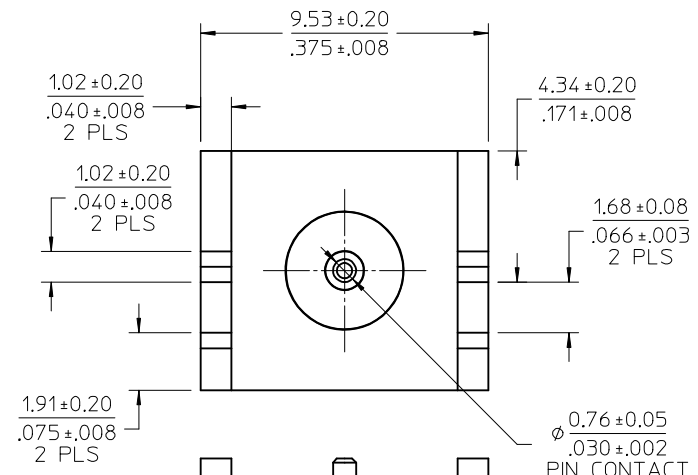
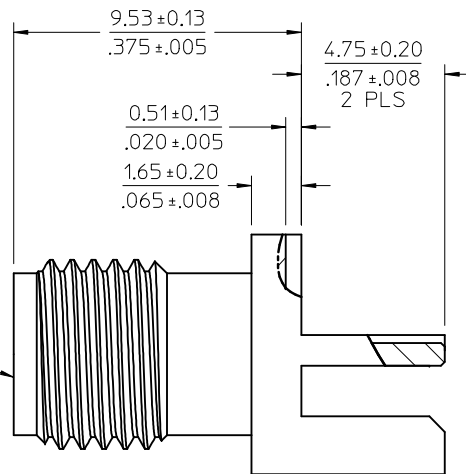
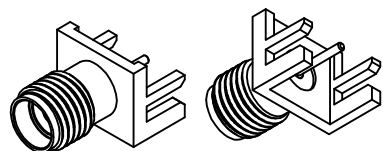
MATERIALS AND FINISHES

BODY BRASS  
PLATED GOLD (SEE TABLE)

CENTER CONTACT BERYLLIUM COPPER  
PLATED GOLD (SEE TABLE)

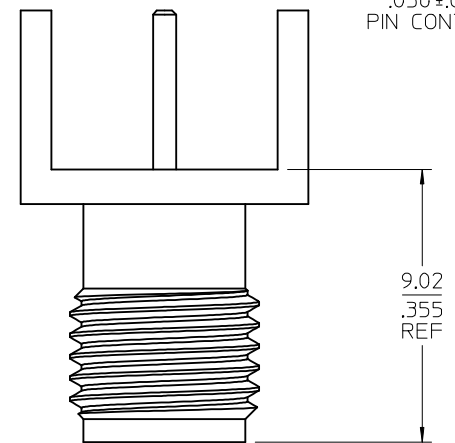
INSULATOR TEFLON

SMA JACK  
INTERFACE



RECOMMENDED MOUNTING PAD

BASE WIDTH: 9.53(.375)  
BOARD THICKNESS: 1.57(.062)  
BOARD MATERIAL: FR4 W/28 g(1.0 OZ) COPPER  
ON BOTTOM (GROUND) SIDE



PS-89675-3460	PRODUCT SPECIFICATION
MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

73251-1153	GOLD FLASH	GOLD 5μ"	TRAY (80 PIECES)	89542-0040
73251-1152	GOLD	GOLD	TRAY (20 PIECES)	89542-0060
73251-1151	GOLD	GOLD	ONE 73251-1150 PER BAG	-----
73251-1150	GOLD	GOLD	TRAY (80 PIECES)	89542-0040
PART NO.	BODY PLATING	CONTACT PLATING	PACKAGING	PART NO.
				PACKAGING

CHG: ADDED PKG  
PN PER EWR 1105

EC NO: URF2018-0013  
DRWN: CWE102  
CHKD:  
APPR: YCHENG

2017/07/20  
2017/08/08

DESCRIPTION

REV

QUALITY SYMBOLS  
=0  
=0

GENERAL TOLERANCES (UNLESS SPECIFIED)  
mm INCH  
4 PLACES ± --- ± ---  
3 PLACES ± --- ± ---  
2 PLACES ± --- ± ---  
1 PLACE ± --- ± ---  
ANGULAR ± 2 °

DRAFT WHERE APPLICABLE  
MUST REMAIN  
WITHIN DIMENSIONS

DIMENSION STYLE  
MM/IN

DRAWN BY  
TEF  
2002/06/27

CHECKED BY  
SSS  
2002/06/27

APPROVED BY  
GMH  
2002/06/27

MATERIAL NO.  
SEE TABLE

SCALE  
INCH

DESIGN UNITS  
INCH

THIRD ANGLE PROJECTION

TITLE  
SMA JACK, EDGE MOUNT  
50 OHMS, EWR-1764  
SMA-J/PCB

MOLEX INCORPORATED

DOCUMENT NO.  
SD-73251-115

SHEET NO.  
1 OF 1

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